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2014年9月

### FPAB30BH60B

# 用于单相升压功率因数校正的 PFC SPM® 3 系列

#### 特性

- 通过 UL 第 E209204 号认证 (UL1557)
- 600 V 30 A 单相升压功率因数校正,包含栅极驱动和保护的控制 IC
- 采用 DBC (Al<sub>2</sub>O<sub>3</sub>) 基板实现非常低的热阻
- 全波桥式整流器和高性能输出二极管
- 内置负温度系数热敏电阻可实现温度监测
- 针对 20 kHz 开关频率进行优化
- 绝缘等级: 2500 Vrms / 分钟

#### 应用

• 单相升压功率因数校正转换器

#### 相关资料

- · AN-9090 PFC SPM 3 Series User's Guide
- · AN-9091 Boost PFC Inductor Design Guide

#### 概述

FPAB30BH60B 是一种先进的 PFC SPM<sup>®</sup> 3 模块,为消费、医药和工业应用提供非常全面的高性能升压功率因数校正输入功率平台。这些单相模块综合优化了内置 IGBT的栅极驱动以最小化电磁干扰和能量损耗。同时也提供多重模组保护特性,集成欠压闭锁,过流保护,热量监测和故障报告。这些模块内的全波整流器和高性能输出二极管,为额外节省空间和方便安装起到了重要作用。

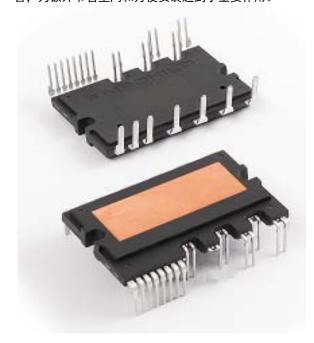


图 1. 封装概览

#### 封装标识与定购信息

器件	器件标识	:4CR::1U   +T.5C		数量
FPAB30BH60B	FPAB30BH60B	SPMIC-027	Rail	10

#### 集成的功率功能

• PFC 转换器,适用于单相 AC/DC 功率变换 (请参见图 3)

#### 集成的驱动、保护和系统控制功能

- 对于 IGBT: 栅极驱动电路、过流保护 (OCP)、控制电源欠压锁定 (UVLO) 保护
- 故障信号:对应 OC 和 UV 故障
- 内置热敏电阻: 温度监控
- 输入接口: 高电平有效接口,可用于 3.3 / 5 V 逻辑电平,施密特触发脉冲输入

#### 引脚配置

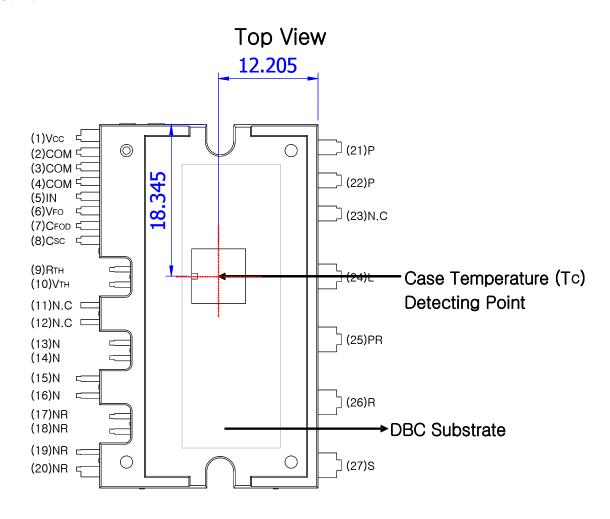


图 2. 俯视图

**注:** 1. 关于壳体温度 (T<sub>C</sub>) 的测量点,请参见图 2。

### 引脚描述

引脚号	引脚名	引脚描述	
1	V <sub>CC</sub>	驱动 IC 和 IGBT 的通用偏置电压	
2,3,4	СОМ	公共电源接地	
5	IN	IGBT 信号输入	
6	V <sub>FO</sub>	故障输出	
7	C <sub>FOD</sub>	设置故障输出持续时间的电容	
8	C <sub>SC</sub>	过电流感测电容 (低通滤波器)	
9	R <sub>(TH)</sub>	供热敏电阻使用的串联电阻器	
10	V <sub>(TH)</sub>	热敏电阻偏压	
11,12	N.C	无连接 <sup>*</sup>	
13~16	N	IGBT 发射极	
17~20	N <sub>R</sub>	整流器直流负端	
21,22	Р	直流正端	
23	N.C	无连接	
24	L	电感器连接引脚	
25	P <sub>R</sub>	整流器直流正端	
26	R	R相的交流输入	
27	S	S相的交流输入	

<sup>\*</sup> 引脚 11 和引脚 12 被切除。更多详细信息请参照产品封装外形图。

### 内部等效电路与输入/输出引脚

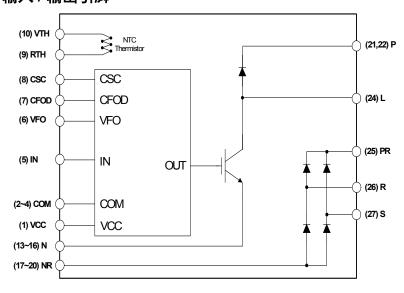


图 3. 内部框图

# **绝对最大额定值** (T<sub>J</sub> = 25°C, 除非另有说明。) **转换器部分**

符号	项目	条件	额定值	单位
V <sub>i</sub>	电源电压	施加在 R - S 之间	264	V <sub>rms</sub>
V <sub>i(浪涌)</sub>	电源电压 (浪涌)	施加在 R - S 之间	500	٧
$V_{PN}$	输出电压	施加在 P - N 之间	450	٧
V <sub>PN(浪涌)</sub>	输出电压 (浪涌)	施加在 P - N 之间	500	>
V <sub>CES</sub>	集电极 - 发射极之间电压		600	>
I <sub>C</sub>	单个 IGBT 的集电极电流	T <sub>C</sub> = 25°C, T <sub>J</sub> < 150°C	30	Α
I <sub>CP</sub>	单个 IGBT 的集电极电流 (峰值)	T <sub>C</sub> = 25°C, T <sub>J</sub> < 150°C, 脉冲宽度小于 1ms	60	Α
P <sub>C</sub>	集电极功耗	T <sub>C</sub> = 25°C	104	W
$V_{RRM}$	重复反向峰值电压		600	٧
I <sub>FSM</sub>	正向浪涌峰值电流	单一正弦半波	350	Α
T <sub>J</sub>	工作结温		-40 ~ 150	°C

#### 控制部分

符号	项目	条件	额定值	单位
V <sub>CC</sub>	控制电源电压	施加在 V <sub>CC</sub> - COM 之间	20	٧
V <sub>IN</sub>	输入信号电压	施加在 IN - COM 之间	-0.3 ~ V <sub>CC</sub> +0.3	٧
V <sub>FO</sub>	故障输出电源电压	施加在 V <sub>FO</sub> - COM 之间	-0.3 ~ V <sub>CC</sub> +0.3	٧
I <sub>FO</sub>	故障输出电流	V <sub>FO</sub> 引脚处的灌电流	5	mA
V <sub>SC</sub>	电流感测输入电压	施加在 C <sub>SC</sub> - COM 之间	-0.3 ~ V <sub>CC</sub> +0.3	V

#### 整个系统

符号	项目	条件	额定值	单位
T <sub>STG</sub>	存储温度		-40 ~ 125	°C
V <sub>ISO</sub>	绝缘电压	60 Hz, 正弦波形, 交流 1 分钟, 连接陶瓷基板 到引脚	2500	V <sub>rms</sub>

#### 热阻

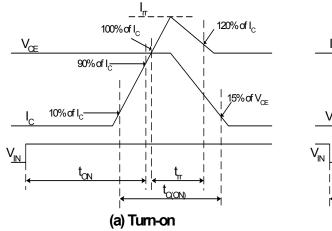
符号	项目	条件	最小值	典型值	最大值	单位
$R_{\theta(j\text{-}c)Q}$	结点 - 壳体的热阻	IGBT	-	1	1.2	°C/W
$R_{\theta(j\text{-}c)F}$		FRD	-	-	1.4	°C/W
$R_{\theta(j-c)R}$		整流器(每1/4模块)	-	1	1.7	°C/W

## 电气特性 $(T_J = 25^{\circ}C, R)$ 除非另有说明。)

#### 转换器部分

符号	项目	条件	最小值	典型值	最大值	单位
V <sub>CE(SAT)</sub>	IGBT 饱和电压	$V_{CC} = 15 \text{ V}, V_{IN} = 5 \text{ V}, I_{C} = 30 \text{ A}$	-	2.2	2.8	V
$V_{FF}$	快速恢复二极管正向电压	I <sub>F</sub> = 30 A	-	1.9	2.6	V
$V_{FR}$	整流器正向电压	I <sub>F</sub> = 30 A	-	1.2	1.5	V
t <sub>ON</sub>	开关时间	V <sub>PN</sub> = 400 V, V <sub>CC</sub> = 15V, I <sub>C</sub> = 30 A	-	500	-	ns
t <sub>C(ON)</sub>		V <sub>IN</sub> = 0 V ↔ 5 V,电感负载	-	200	-	ns
t <sub>OFF</sub>		(注 2)	-	420	-	ns
t <sub>C(OFF)</sub>			-	100	-	ns
t <sub>rr</sub>			-	60	-	ns
I <sub>rr</sub>			-	7	-	Α
I <sub>CES</sub>	集电极 - 发射极间漏电流	V <sub>CE</sub> = V <sub>CES</sub>	-	-	250	μА

注:
2.  $t_{ON}$  和  $t_{OFF}$  包括模块内部驱动 IC 的传输延迟时间。  $t_{C(ON)}$  和  $t_{C(OFF)}$  指在内部给定的栅极驱动条件下, IGBT 本身的开关时间。详细信息,请参见图 4。



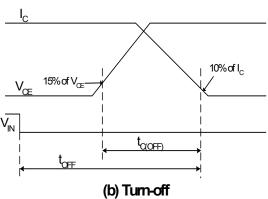


图 4. 开关时间的定义

#### 控制部分

符号	项目	条件	最小值	典型值	最大值	单位
I <sub>QCCL</sub>	V <sub>CC</sub> 静态电源电流	V <sub>CC</sub> = 15 V, IN = 0 V V <sub>CC</sub> - COM	1	-	26	mA
V <sub>FOH</sub>	故障输出电压	V <sub>SC</sub> = 0 V, V <sub>FO</sub> 电路: 4.7 kΩ 至 5 V 上拉	4.5	-	1	>
V <sub>FOL</sub>		V <sub>SC</sub> = 1 V, V <sub>FO</sub> 电路: 4.7 kΩ 至 5 V 上拉	1	-	0.8	>
V <sub>SC(ref)</sub>	过电流保护触发电平	V <sub>CC</sub> = 15 V	0.45	0.50	0.55	>
UV <sub>CCD</sub>	电源电路欠压保护	检测电平	10.7	11.9	13.0	٧
UV <sub>CCR</sub>		复位电平	11.2	12.4	13.2	>
t <sub>FOD</sub>	故障输出脉宽	C <sub>FOD</sub> = 33 nF (注 3)	1.4	1.8	2.0	ms
V <sub>IN(ON)</sub>	导通阈值电压	施加在 IN - COM 之间	2.8	-	-	٧
V <sub>IN(OFF)</sub>	关断阈值电压		1	-	0.8	<b>V</b>
R <sub>TH</sub>	热敏电阻的阻值	当 T <sub>TH</sub> = 25°C 时(注 4,图 5)	-	47.0	-	kΩ
		当 T <sub>TH</sub> = 100°C 时(注 4,图 5)	-	2.9	-	kΩ

**注:** 3. 故障输出脉宽  $t_{FOD}$  取决于电容  $C_{FOD}$  的值,可采用下面的近似公式进行计算: $C_{FOD}$  = 18.3 x 10<sup>-6</sup> x  $t_{FOD}$  [F]。 4.  $T_{TH}$  是壳体温度 ( $T_{C}$ ) 的温度,请根据具体应用进行试验。

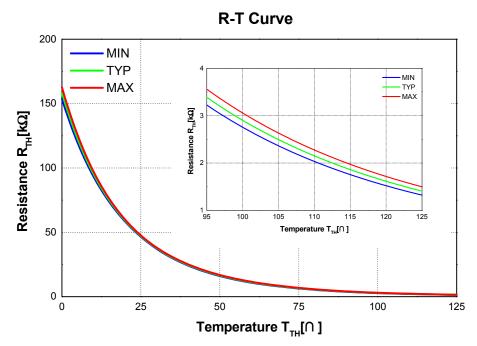


图 5. 内置热敏电阻的 R-T 曲线

## 推荐工作条件

符号	项目	条件	最小值	典型值	最大值	单位
V <sub>i</sub>	输入电源电压	施加在 R - S 之间	187	220	253	$V_{rms}$
V <sub>PN</sub>	输出电压	施加在 P - N 之间	-	380	400	٧
V <sub>CC</sub>	控制电源电压	施加于 V <sub>CC(L)</sub> - COM 之间	13.5	15.0	16.5	٧
dV <sub>CC</sub> /dt	控制电源波动		-1	-	1	V/μs
f <sub>PWM</sub>	PWM 输入频率	$T_{J} \le 150$ °C	-	20	-	kHz
l <sub>i</sub>	允许的输入电流	T <sub>C</sub> < 90°C, V <sub>i</sub> = 220 V, V <sub>PN</sub> = 380 V V <sub>PWM</sub> = 20 kHz	-	-	30	A <sub>peak</sub>

### 机械特性和额定值

项目		<del>条件</del>	最小值	典型值	最大值	单位
安装扭矩	安装螺钉: M3	建议 0.62 N•m	0.51	0.62	0.72	N•m
器件平面度	见图 6		0	-	+120	μm
重量			-	15.00	-	g

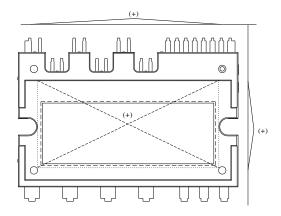
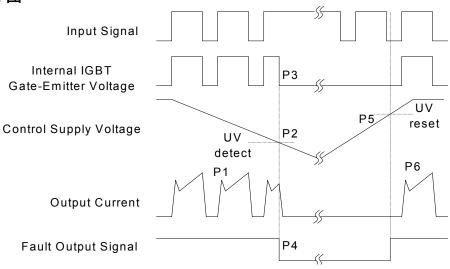


图 6. 平面度测量位置

#### 保护功能时序图

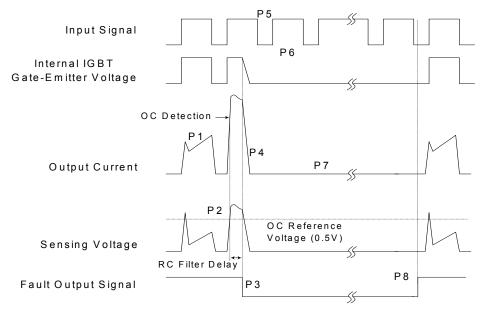


P1:正常工作: IGBT 导通并传导电流。

P2:欠压检测。 P3:IGBT栅极中断。 P4:故障信号产生。 P5:欠压复位。

P6:正常工作: IGBT 导通并传导电流。

图 7. 欠压保护



P1:正常工作: IGBT 导通并传导电流。

P2:过流检测。

P3:IGBT 栅极中断 / 故障信号产生。

P4:IGBT 缓慢关断。

P5:IGBT 关断信号。

P6:IGBT 导通信号:但是在故障输出有效的时间内, IGBT 不导通。

P7:IGBT 关断状态。

P8: 故障输出复位并启动正常工作。

图 8. 过流保护

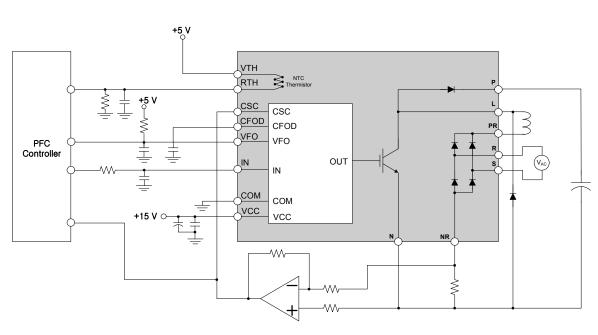
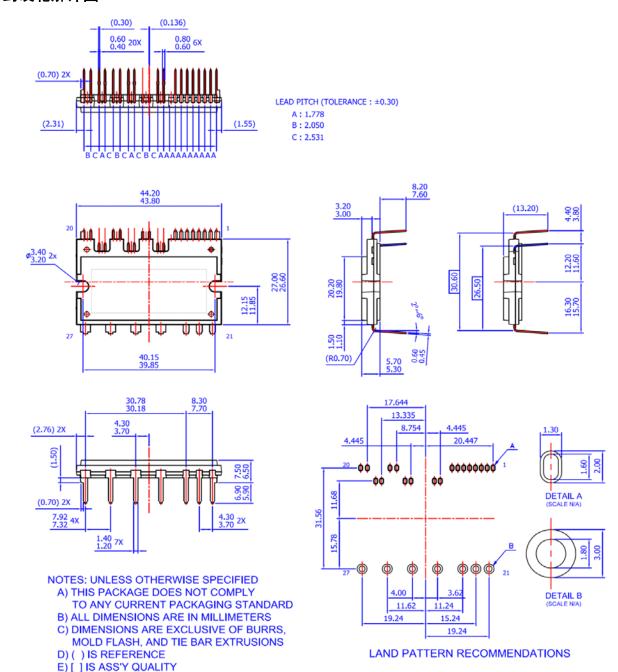


图 9. 应用实例

#### 注:

- 5. 每个电容都应尽可能地靠近 PFC SPM<sup>®</sup> 产品的引脚安装。 6. 建议将反向并联二极管与 IGBT 相连接。

#### 封装轮廓详图



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